

RESIN COMPOSITION FOR ENCAPSULATION AND ELECTRONIC DEVICE USING THE
SAME

ABSTRACT

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The present invention provides a resin composition for encapsulating electronic components that contains a phenol resin curing agent and an epoxy resin, in which either the phenol resin curing agent or the epoxy resin has a biphenyl structure; a resin
10 composition for encapsulating electronic components that contains a phenol resin curing agent and an epoxy resin, in which a glass transition temperature of a cured material is equal to or higher than 200°C, and a weight reduction rate of the cured material is equal to or lower than 0.3%; and an electronic device that includes an
15 electronic component encapsulated with the resin composition.

[FIG. 1]